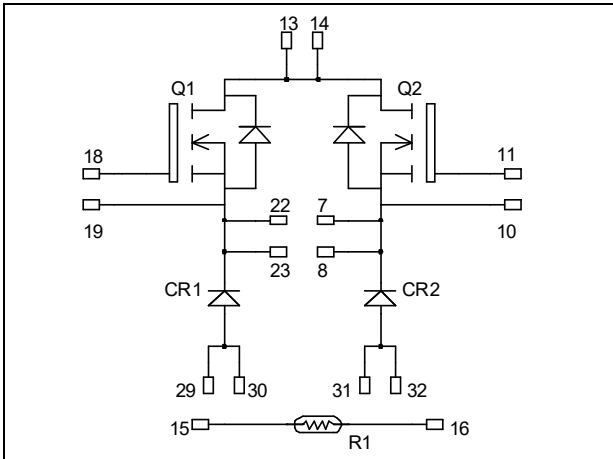


Dual Buck chopper MOSFET Power Module

V_{DSS} = 1000V
R_{DSon} = 350mΩ typ @ T_j = 25°C
I_D = 22A @ T_c = 25°C



Application

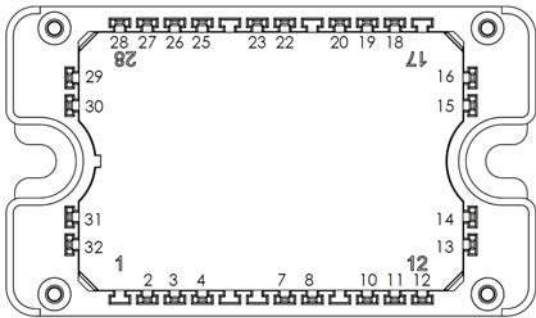
- AC and DC motor control
- Switched Mode Power Supplies

Features

- **Power MOS 7[®] MOSFETs**
 - Low R_{DSon}
 - Low input and Miller capacitance
 - Low gate charge
 - Avalanche energy rated
 - Very rugged
- Kelvin source for easy drive
- Very low stray inductance
- Internal thermistor for temperature monitoring

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Low profile
- Each leg can be easily paralleled to achieve a single buck of twice the current capability
- RoHS Compliant



All multiple inputs and outputs must be shorted together
 Example: 13/14 ; 29/30 ; 22/23 ...

All ratings @ T_j = 25°C unless otherwise specified

Absolute maximum ratings (per MOSFET)

Symbol	Parameter	Max ratings	Unit
V _{DSS}	Drain - Source Voltage	1000	V
I _D	Continuous Drain Current	T _c = 25°C	22
		T _c = 80°C	17
I _{DM}	Pulsed Drain current	88	
V _{GS}	Gate - Source Voltage	±30	V
R _{DSon}	Drain - Source ON Resistance	420	mΩ
P _D	Power Dissipation	T _c = 25°C	390
I _{AR}	Avalanche current (repetitive and non repetitive)	25	A
E _{AR}	Repetitive Avalanche Energy	50	mJ
E _{AS}	Single Pulse Avalanche Energy	3000	

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

Electrical Characteristics (per MOSFET)

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
I _{DSS}	Zero Gate Voltage Drain Current	V _{GS} = 0V, V _{DS} = 1000V			100	μA
R _{DS(on)}	Drain – Source on Resistance	V _{GS} = 10V, I _D = 11A		350	420	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} = V _{DS} , I _D = 2.5mA	3		5	V
I _{GSS}	Gate – Source Leakage Current	V _{GS} = ±30V, V _{DS} = 0V			±150	nA

Dynamic Characteristics (per MOSFET)

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C _{iss}	Input Capacitance	V _{GS} = 0V		5.2		nF
C _{oss}	Output Capacitance	V _{DS} = 25V		0.88		
C _{rss}	Reverse Transfer Capacitance	f = 1MHz		0.16		
Q _g	Total gate Charge	V _{GS} = 10V		186		nC
Q _{gs}	Gate – Source Charge	V _{Bus} = 500V		24		
Q _{gd}	Gate – Drain Charge	I _D = 22A		122		
T _{d(on)}	Turn-on Delay Time	Inductive switching @ 125°C V _{GS} = 15V V _{Bus} = 670V I _D = 22A R _G = 5Ω		18		ns
T _r	Rise Time			12		
T _{d(off)}	Turn-off Delay Time			155		
T _f	Fall Time			40		
E _{on}	Turn-on Switching Energy	Inductive switching @ 25°C V _{GS} = 15V, V _{Bus} = 670V I _D = 22A, R _G = 5Ω		900		μJ
E _{off}	Turn-off Switching Energy			623		
E _{on}	Turn-on Switching Energy	Inductive switching @ 125°C V _{GS} = 15V, V _{Bus} = 670V I _D = 22A, R _G = 5Ω		1423		μJ
E _{off}	Turn-off Switching Energy			779		
R _{thJC}	Junction to Case Thermal Resistance				0.32	°C/W

Chopper Diode ratings and characteristics (per diode)

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
V _{RRM}	Peak Repetitive Reverse Voltage				1000	V
I _{RM}	Reverse Leakage Current	V _R = 1000V			250	μA
I _F	DC Forward Current	T _c = 70°C		30		A
V _F	Diode Forward Voltage	I _F = 30A		1.9	2.3	V
		I _F = 60A		2.2		
		I _F = 30A, T _j = 125°C		1.7		
t _{rr}	Reverse Recovery Time	I _F = 30A V _R = 667V di/dt = 200A/μs	T _j = 25°C	290		ns
			T _j = 125°C	390		
Q _{rr}	Reverse Recovery Charge	I _F = 30A V _R = 667V di/dt = 200A/μs	T _j = 25°C	670		nC
			T _j = 125°C	2350		
R _{thJC}	Junction to Case Thermal Resistance				1.2	°C/W

Thermal and package characteristics

Symbol	Characteristic	Min	Max	Unit		
V _{ISOL}	RMS Isolation Voltage, any terminal to case t=1 min, 50/60Hz	4000		V		
T _J	Operating junction temperature range	-40	150	°C		
T _{JOP}	Recommended junction temperature under switching conditions	-40	T _{Jmax} - 25			
T _{STG}	Storage Temperature Range	-40	125			
T _C	Operating Case Temperature	-40	125			
Torque	Mounting torque	To heatsink	M4	2	3	N.m
Wt	Package Weight				110	g

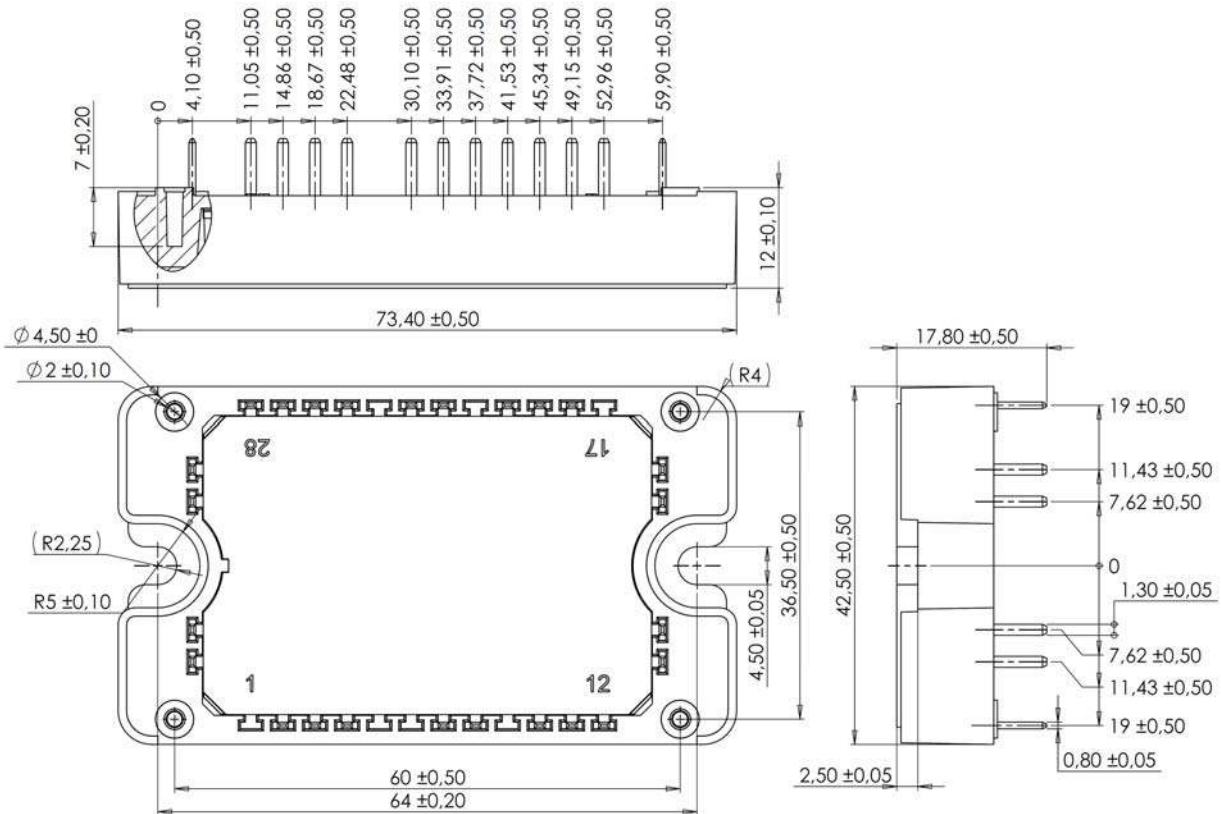
Temperature sensor NTC (see application note APT0406 on www.microsemi.com for more information).

Symbol	Characteristic	Min	Typ	Max	Unit
R ₂₅	Resistance @ 25°C		50		kΩ
ΔR ₂₅ /R ₂₅			5		%
B _{25/85}	T ₂₅ = 298.15 K		3952		K
ΔB/B			4		%

$$R_T = \frac{R_{25}}{\exp\left[B_{25/85}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]}$$

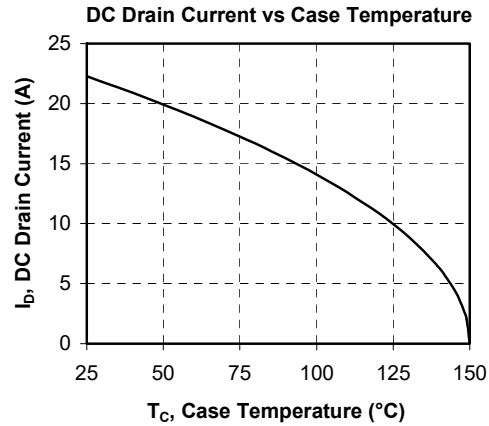
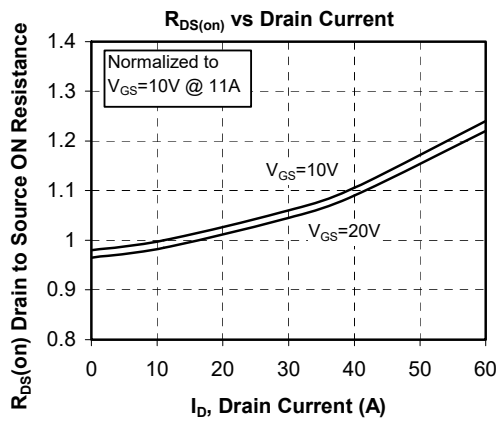
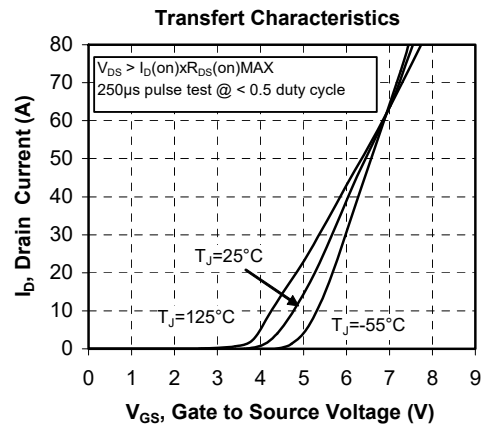
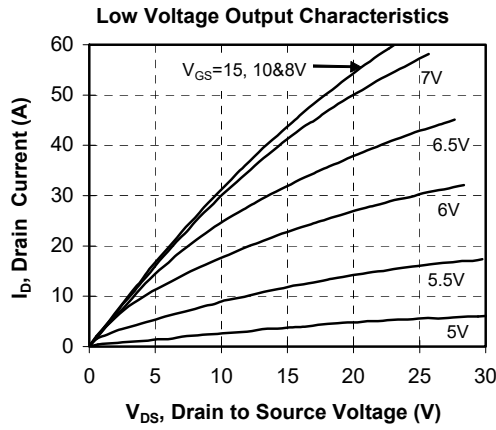
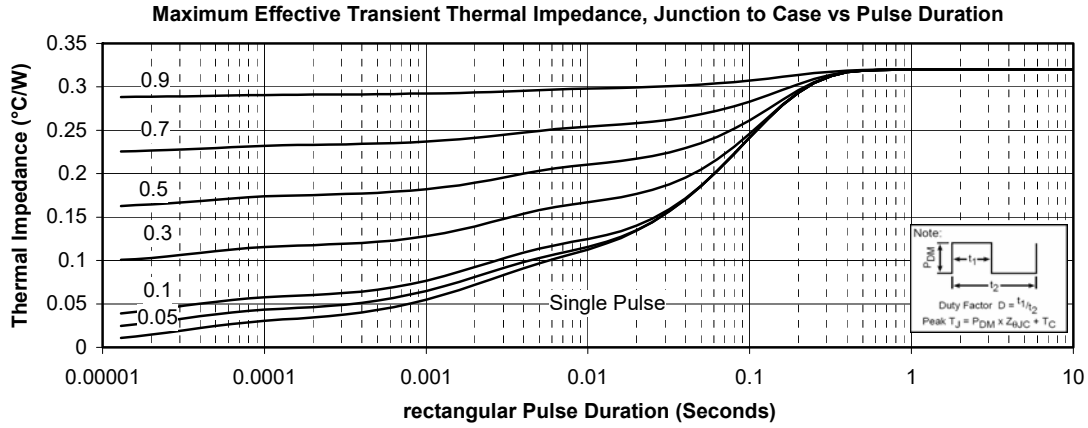
T: Thermistor temperature
R_T: Thermistor value at T

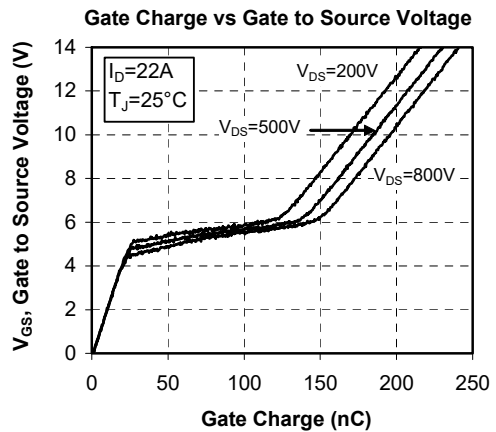
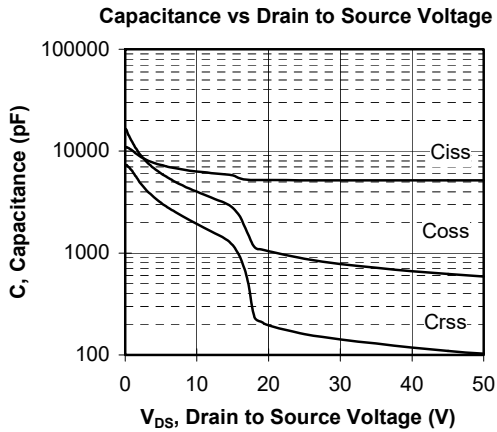
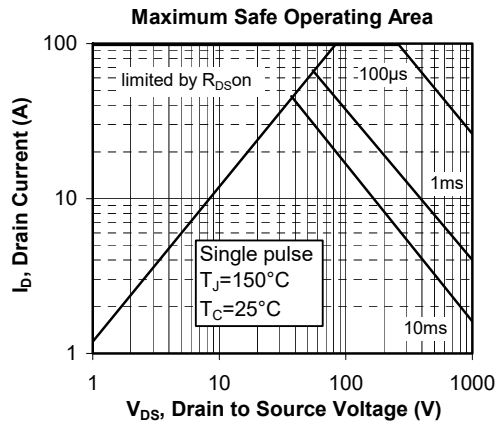
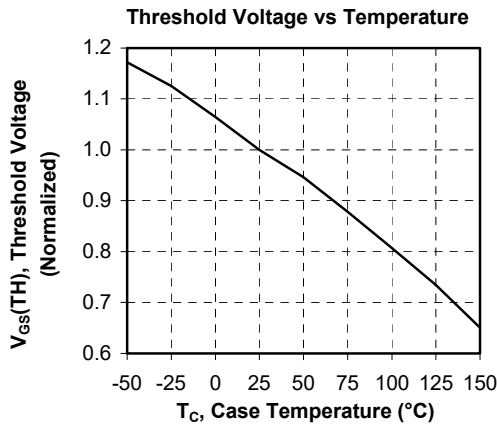
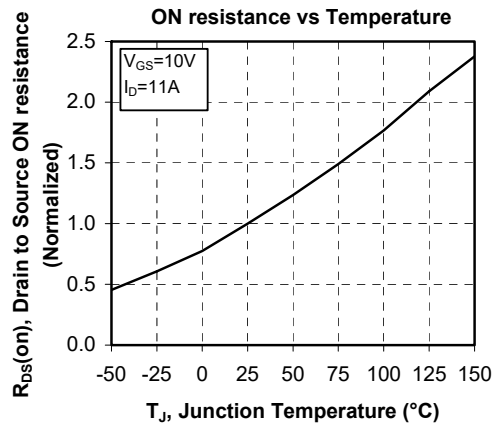
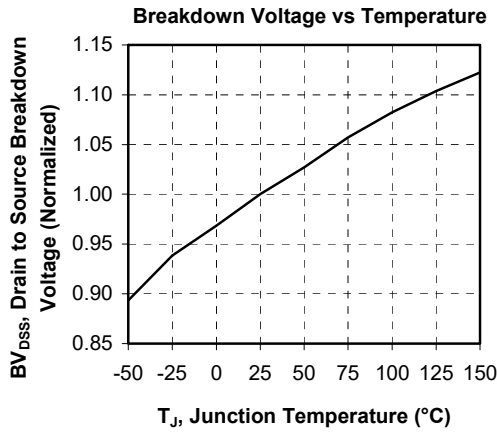
Package outline (dimensions in mm)

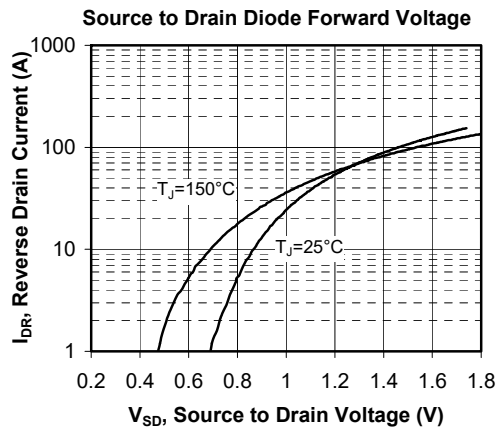
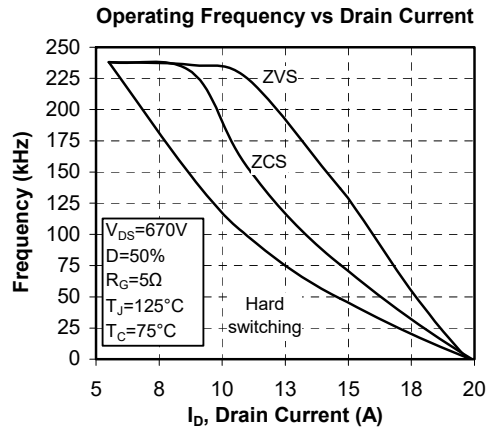
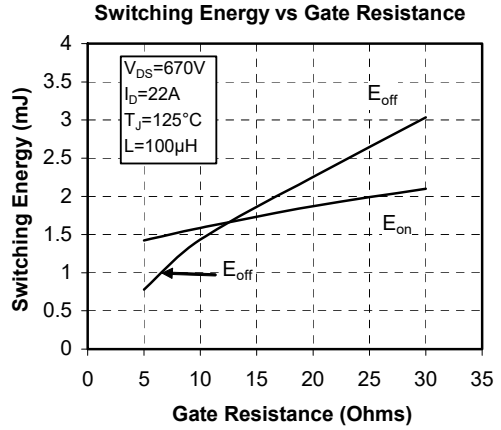
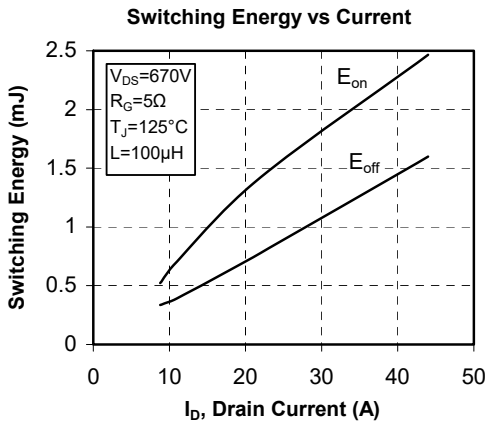
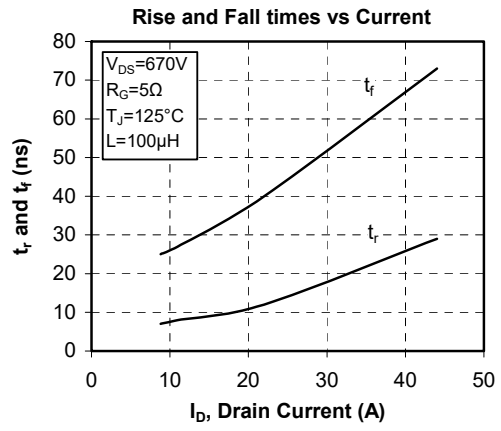
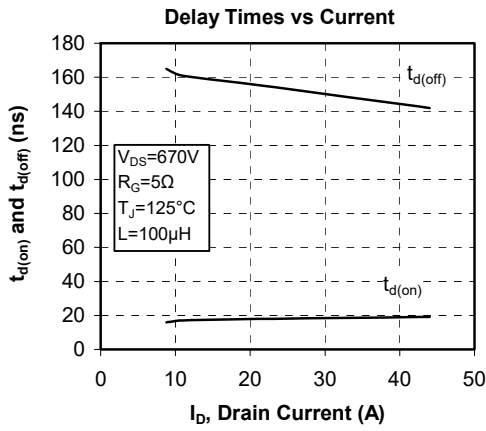


See application note 1906 - Mounting Instructions for SP3F Power Modules on www.microsemi.com

Typical Performance Curve







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